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WHAT IS CLAIMED IS:

1. A method of securing a panel with an adhesive bonding material, using hand-held operator manipulatable dispensing device to dispense adhesive bonding material via a dispensing outlet of the device, the method comprising subjecting the bonding material to a predetermined temperature regime, the predetermined temperature regime having:

(i) a period of heating the bonding material at a predetermined level prior to dispensing from the dispensing outlet of the device; and

(ii) a subsequent period of curing in-situ in contact with the glazing panel at a temperature significantly below the heating temperature level in step (i); wherein

the temperature of the adhesive bonding material dispensed via the dispensing outlet is maintained substantially uniform as adhesive is dispensed about the periphery of the panel.

2. A method according to claim 1, wherein the adhesive bonding material is a moisture cure adhesive bonding material.

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3. A method according to claim 1, wherein the predetermined level to which the adhesive bonding material is heated prior to dispensing from the dispensing device is substantially at or above 50°C.
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4. A method according to claim 1, wherein the predetermined level to which the adhesive bonding material is heated prior to dispensing from the dispensing device is substantially in the range 70°C ±
- 10 20°C.
5. A method according to claim 1, wherein the temperature of the adhesive bonding material as dispensed is maintained at a uniform temperature ± 5°C during dispensing about a panel or the frame to which the panel is to be bonded.
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6. A method according to claim 1, wherein the uniform dispensing temperature of the adhesive bonding material dispensed from the device is 70°C ± 20°C.
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7. A method according to claim 1, wherein a minor degree of curing of the adhesive bonding material occurs during the in applicator device heating stage.
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8. A method according to claim 1, wherein a bulk heating technique is utilised to heat the adhesive bonding material.
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9. A method according to claim 1, wherein dielectric heating is used to heat the adhesive bonding material.
- 5 10. A method according to claim 1, wherein microwave heating is used to heat the adhesive bonding material.
11. A method according to claim 1, wherein Radio Frequency heating is used to heat the adhesive bonding material.
- 10 12. A method according to claim 1, wherein ultrasonic heating is used to heat the adhesive bonding material.
13. A method according to claim 1, wherein heating by electromagnetic radiation is used to heat the adhesive bonding material.
- 15 14. A method according to claim 1, wherein following the heating stage and dispensing the adhesive bonding material applied to secure the panel is permitted to cure in situ in ambient conditions.
- 20 15. A method according to claim 1, wherein the heating stage is carried out prior to positioning the panel and adhesive bonding material for securing.
- 25 16. An applicator device for dispensing adhesive material, the applicator device being hand-held and operator manipulatable and comprising a body portion including a delivery channel for delivery of adhesive bonding material to a dispensing outlet nozzle, the body portion further including an operator actuatable
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heating arrangement for heating the adhesive bonding material in the channel, internally of the device to a predetermined temperature level to produce a substantially constant outlet dispensing temperature via the nozzle.

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17. An applicator device according to claim 16, including a drive arrangement to urge the adhesive material along the delivery channel toward the outlet nozzle, actuation of the drive arrangement and the heating arrangement being by means of a common operator manipulatable actuator.

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18. An applicator device according to claim 16, wherein the heating arrangement is self-contained in a body portion of the applicator device positioned forwardly of the operator manipulatable actuator.

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19. An applicator device according to claim 16, wherein the heating arrangement comprises a dielectric heating arrangement to heat the adhesive bonding material.

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20. An applicator device according to claim 16, wherein the heating arrangement comprises a microwave heating arrangement to heat the adhesive bonding material.

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21. An applicator device according to claim 16, wherein the heating arrangement comprises a Radio Frequency heating arrangement to heat the adhesive bonding material.

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22. An applicator device according to claim 16, wherein the heating arrangement comprises an ultrasonic heating arrangement to heat the adhesive bonding material.

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23. An applicator device according to claims 16, wherein the device is configured to accept the adhesive material in canister or package form.

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